

Product Change Notice

Last Update: 2019/10/22

PAPS Announcement:

We have recently received product change notice from manufacturer for the following products. This announcement takes effective immediately. Please review this notice carefully and contact with product manager or your regional PAPS representatives, should you have any question.

Description of the Change

Samsung DDR4 DRAMs technology migration.

Die change - 512Mb* 8 IC from E die to F die ; 1Gb*8 IC from B die to C die

Effective Date	Start Date	Last Shipment Date	Cut-in Implementation
2020/01/01	Running Change	Running Change	Running Change

Affected Products:

Part Number	Product Description
AQD-D4U4GN24-SG	Advantech 4G DDR4-2400 288Pin 512X8 1.2V Samsung Chip
AQD-D4U8GN24-SE	Advantech 8G DDR4-2400 288Pin 1GX8 1.2V Samsung Chip
AQD-D4U16N24-SE	Advantech 16G DDR4-2400 288Pin 1GX8 1.2V Samsung Chip
AQD-SD4U4GN24-SG	Advantech 4G SO-DDR4-2400 260Pin 512X8 1.2V Samsung Chip
AQD-SD4U8GN24-SE	Advantech 8G SO-DDR4-2400 260Pin 1GX8 1.2V Samsung Chip
AQD-SD4U16N24-SE	Advantech 16G SO-DDR4-2400 260Pin 1GX8 1.2V Samsung Chip
AQD-D4U4GN26-SG	Advantech 4G DDR4-2666 512X8 1.2V Samsung Chip
AQD-D4U8GN26-SE	Advantech 8G DDR4-2666 1GX8 1.2V Samsung Chip
AQD-D4U16N26-SE	Advantech 16G DDR4-2666 1GX8 1.2V Samsung Chip
AQD-SD4U4GN26-SG	Advantech 4G SO-DDR4-2666 512X8 1.2V Samsung Chip
AQD-SD4U8GN26-SE	Advantech 8G SO-DDR4-2666 1GX8 1.2V Samsung Chip
AQD-SD4U16N26-SE	Advantech 16G SO-DDR4-2666 1GX8 1.2V Samsung Chip

*Should you have any question regarding products, please contact PM, Lindsay Chou (lindsay.chou@advantech.com.tw ; 511-7931) or your regional buyers for purchasing information.